xfab

X-FAB Global Services GmbH · Haarbergstr. 67 · 99097 Erfurt

X-FAB Product Declaration

In line with the Environmental, Health and Safety Policy of X-FAB, we are continuously working on the reduction of our environmental impact in accordance with the legal requirements.

Restriction of Hazardous Substances (RoHS)

X-FAB hereby confirms that its wafers are free from "intentionally introduced" lead, cadmium, mercury, hexavalent chromium, polybrominated biphenyls (PBB), polybrominated diphenyl ethers (PBDE), bis(2-ethylhexyl) phthalate (DEHP), butyl benzyl phthalate (BBP), dibutyl phthalate (DBP) or diisobutyl phthalate (DIBP) as defined in Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment and all its amendments thereto.

Registration, Evaluation, Authorisation and restriction of Chemicals (REACH)

Wafers produced by X-FAB are classified as Articles under REACH (Registration, Evaluation, Authorisation and Restriction of Chemicals) Regulation EC/1907/2006.

X-FAB hereby confirms that its wafers are free from:

- 1. Any of the substances in the Candidate List of Substances of Very High Concern (SVHC). This includes the 240 substances announced by ECHA on 23 January 2024.
- 2. Any of the substances mentioned in Annex XVII and XIV of REACH regulation.

Halogen Free (Bromine & Chlorine)

X-FAB hereby confirms that its wafers are free from halogen (bromine and chlorine) as defined under IEC 61249-2-21.

Sourcing and usage of rare earth elements

X-FAB refers to rare earth elements as described in <u>https://geology.com/articles/rare-earth-elements/</u>. X-FAB declares that its wafers are free from rare earth elements. If traces of such elements are contained in supplied process chemicals, X-FAB will take the necessary actions to secure worldwide supply within standard practices and legal requirements.

Sourcing materials from Conflict Regions

We, X-FAB group of companies are aware of the Dodd-Frank Wall Street Reform and Consumer Protection Act (Wall Street Reform Act) requirements regarding the sourcing of metals (tin, tantalum, tungsten, gold) from conflict regions. All our X-FAB manufacturing sites will request, all our relevant suppliers to source for minerals from certified conflict-free smelters validated as compliant by RMAP (Responsible Minerals Assurance Process) protocol. X-FAB uses the list of compliant smelters available at the Responsibility Minerals Initiative website to verify that the smelter is RMAP conformant. This list is available on http://www.responsiblemineralsinitiative.org

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According to the information collected from our suppliers, the minerals sourced from mines in conflict regions (Democratic Republic of Congo (DRC) and its neighbouring countries), are certified to be conflict-free. As the list of RMAP Conformant Smelters is subject to change based on the supplier conformance and incorporation of new requirements, we will update our information from time to time. If we become aware that our supply chain includes minerals from DRC or adjoining countries, we will take prompt action to review such findings and to take the necessary actions, as appropriate.

Dirk Neuhaus

Global Manager QM Systems, Group Responsible for EHS 24 January 2024

About X-FAB

X-FAB is the leading analog/mixed-signal and MEMS foundry group manufacturing silicon wafers for automotive, industrial, consumer, medical and other applications. Its customers worldwide benefit from the highest quality standards, manufacturing excellence and innovative solutions by using X-FAB's modular CMOS and SOI processes in geometries ranging from 1.0 to 0.13 µm, and its special SiC and MEMS long-lifetime processes. X-FAB's analog-digital integrated circuits (mixed-signal ICs), sensors and micro-electro-mechanical systems (MEMS) are manufactured at six production facilities in Germany, France, Malaysia and the U.S. X-FAB employs about 3,800 people worldwide. www.xfab.com

X-FAB EHS Contacts

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